

PCM 16125C KERATHERM®

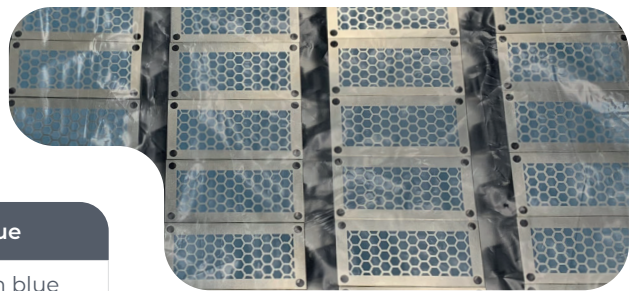
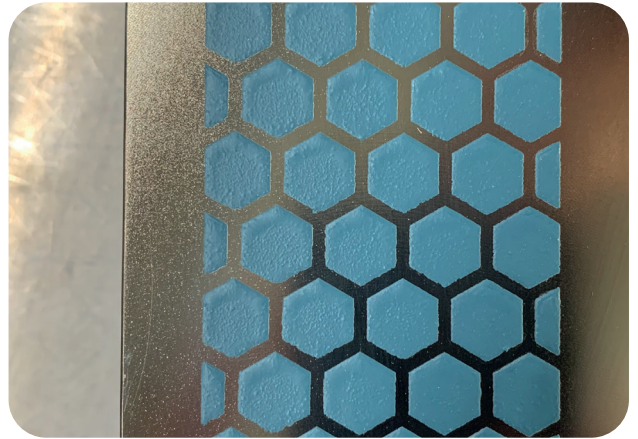
NEW
DATA SHEET

Application

- Thyristors
- Desktop CPU´s
- IGBT units

Benefits

- Filling of smallest irregularities between the power module and heat sink
- Improves the contact between the surfaces and increases the heat transfer
- Good applicability in the form of screen and stencil printing
- Possibility to buy pre assembled parts
- Very low bond line thickness



Properties	Unit	Value
Colour		Titanium blue
Viscosity Brookfield K/P* (Temperature dependent; dried area)	Pas	400/creamy (@40°C) 200 (@50°C) 120 (@60°C) 80 (@80°C) 50 (@100°C)
Thermal conductivity λ	W/mK	>3.5
Dielectric breakdown E_d	kV	>1
Operating temperature	°C	-40 to +120
Softening interval	°C	52 -54
Possible layer thickness	μm	50 -250
Post-curing time (40°C @ 250 μm)**	h	18 -24

* Sheare rate λ 4.6s⁻¹

** This time is valid for natural convection.If there is some kind of ventilation, the time curing time is lower